

## N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTORS

PRELIMINARY DATA

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STW8NA80	800 V	< 1.50 Ω	7.2 A
STH8NA80FI	800 V	< 1.50 Ω	4.5 A

- TYPICAL R<sub>DS(on)</sub> = 1.3 Ω
- ± 30V GATE TO SOURCE VOLTAGE RATING
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW INTRINSIC CAPACITANCES
- GATE CHARGE MINIMIZED
- REDUCED THRESHOLD VOLTAGE SPREAD

### DESCRIPTION

This series of POWER MOSFETS represents the most advanced high voltage technology. The optimized cell layout coupled with a new proprietary edge termination concur to give the device low R<sub>DS(on)</sub> and gate charge, unequalled ruggedness and superior switching performance.

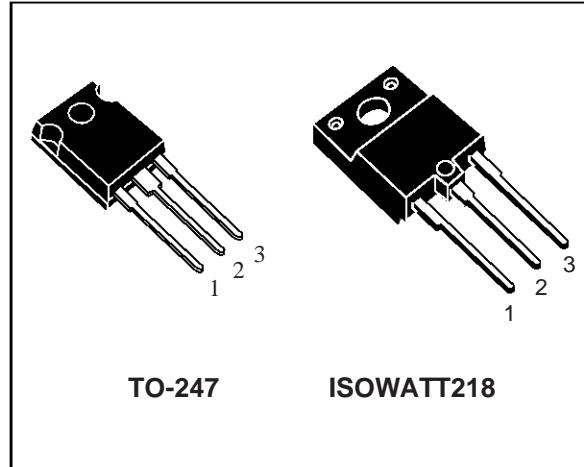
### APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DRIVE

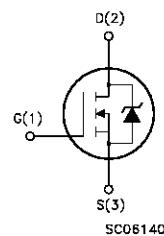
### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STW8NA80	STH8NA80FI	
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	800	800	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	800	800	V
V <sub>GS</sub>	Gate-source Voltage	± 30	± 30	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 25 °C	7.2	4.5	A
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 100 °C	4.5	2.8	A
I <sub>DM(•)</sub>	Drain Current (pulsed)	28.8	28.8	A
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	175	70	W
	Derating Factor	1.4	0.56	W/°C
V <sub>ISO</sub>	Insulation Withstand Voltage (DC)	—	4000	V
T <sub>stg</sub>	Storage Temperature	-65 to 150		°C
T <sub>j</sub>	Max. Operating Junction Temperature	150		°C

(•) Pulse width limited by safe operating area



### INTERNAL SCHEMATIC DIAGRAM



## STW8NA80 STH8NA80FI

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### THERMAL DATA

			TO-247	ISOWATT218	
R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	0.71	1.78	°C/W
R <sub>thj-amb</sub> R <sub>thc-sink</sub>	Thermal Resistance Junction-ambient Thermal Resistance Case-sink	Max Typ	30 0.1	300	°C/W °C/W °C
T <sub>I</sub>	Maximum Lead Temperature For Soldering Purpose				

### AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max, δ < 1%)	7.2	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	700	mJ

### ELECTRICAL CHARACTERISTICS (T<sub>case</sub> = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA V <sub>GS</sub> = 0	800			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating T <sub>c</sub> = 100 °C			50 500	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 30 V			100	nA

ON (\*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 250 μA	2.25	3	3.75	V
R <sub>D(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10V I <sub>D</sub> = 4A		1.3	1.5	Ω
I <sub>D(on)</sub>	On State Drain Current	V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>D(on)max</sub> V <sub>GS</sub> = 10 V	7.2			A

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>D(on)max</sub> I <sub>D</sub> = 4 A	4.5	7.9		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>DS</sub> = 25 V f = 1 MHz V <sub>GS</sub> = 0		1750 188 50	2300 245 70	pF pF pF

**ELECTRICAL CHARACTERISTICS** (continued)

## SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$	Turn-on Time Rise Time	$V_{DD} = 400 \text{ V}$ $R_G = 4.7 \Omega$ $I_D = 4 \text{ A}$ $V_{GS} = 10 \text{ V}$		20 28	28 38	ns ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 640 \text{ V}$ $R_G = 47 \Omega$ $I_D = 8 \text{ A}$ $V_{GS} = 10 \text{ V}$		170		A/ $\mu\text{s}$
$Q_g$ $Q_{gs}$ $Q_{gd}$	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 400 \text{ V}$ $I_D = 8 \text{ A}$ $V_{GS} = 10 \text{ V}$		75 10 35	100	nC nC nC

## SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(V_{off})}$ $t_f$ $t_c$	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 640 \text{ V}$ $R_G = 4.7 \Omega$ $I_D = 8 \text{ A}$ $V_{GS} = 10 \text{ V}$		18 20 25	25 28 35	ns ns ns

## SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$ $I_{SDM}(\bullet)$	Source-drain Current Source-drain Current (pulsed)				7.2 28.8	A A
$V_{SD} (\ast)$	Forward On Voltage	$I_{SD} = 7.2 \text{ A}$ $V_{GS} = 0$			1.6	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 7.5 \text{ A}$ $V_{DD} = 100 \text{ V}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $T_j = 150 \text{ }^\circ\text{C}$		850 17 40		ns $\mu\text{C}$ A

(\ast) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %

(\bullet) Pulse width limited by safe operating area